MBRB2515L

Preferred Device

SWITCHMODE™ Power Rectifier ORing Function Diode

D²PAK Surface Mount Power Package

The D²PAK Power Rectifier employs the Schottky Barrier principle in a large metal-to-silicon power diode. State-of-the-art geometry features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for use in low voltage, high frequency switching power supplies, free wheeling diodes, and polarity protection diodes.

Features

- Guardring for Stress Protection
- Low Forward Voltage
- 100°C Operating Junction Temperature
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Short Heat Sink Tab Manufactured Not Sheared
- Similar in Size to the Industry Standard TO-220 Package
- Pb-Free Packages are Available

Mechanical Characteristics:

- Case: Epoxy, Molded, Epoxy Meets UL 94 V-0
- Weight: 1.7 Grams (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Device Meets MSL1 Requirements
- ESD Ratings: Machine Model, C (>400 V)

Human Body Model, 3B (>8000 V)

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	15	٧
Average Rectified Forward Current (Rated V_R , $T_C = 90$ °C)	I _{F(AV)}	25	Α
Peak Repetitive Forward Current (Rated V _R , Square Wave, 20 kHz, T _C = 100°C)	I _{FRM}	30	Α
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I _{FSM}	150	Α
Storage Temperature Range	T _{stg}	-65 to +150	°C
Operating Junction Temperature	TJ	100	°C
Voltage Rate of Change (Rated V _R)	dv/dt	10,000	V/μs

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.



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SCHOTTKY BARRIER RECTIFIER 25 AMPERES, 15 VOLTS





D²PAK CASE 418B STYLE 3

MARKING DIAGRAM



A = Assembly Location

/ = Year

WW = Work Week
B2515L = Device Code
G = Pb-Free Package
AKA = Diode Polarity

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

Preferred devices are recommended choices for future use and best overall value.

MBRB2515L

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance, – Junction-to-Case – Junction-to-Ambient (Note 1)	$egin{array}{c} {\sf R}_{ heta {\sf JC}} \ {\sf R}_{ heta {\sf JA}} \end{array}$	1.0 50	°C/W

^{1.} When mounted using minimum recommended pad size on FR-4 board.

ELECTRICAL CHARACTERISTICS

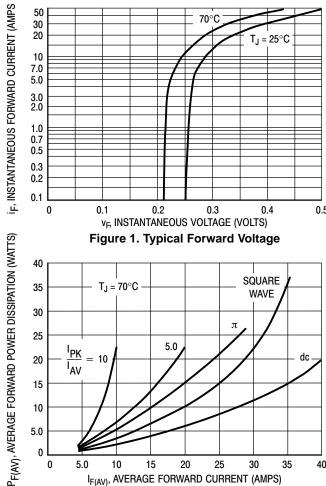
Characteristic	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage (Note 2) ($i_F = 19$ Amps, $T_J = 70^{\circ}$ C) ($i_F = 25$ Amps, $T_J = 70^{\circ}$ C) ($i_F = 25$ Amps, $T_J = 25^{\circ}$ C)	VF	0.38 0.42 0.45	V
Maximum Instantaneous Reverse Current (Note 2) (Rated dc Voltage, $T_J = 70^{\circ}\text{C}$) (Rated dc Voltage, $T_J = 25^{\circ}\text{C}$)	I _R	200 15	mA

^{2.} Pulse Test: Pulse Width = 300 μs, Duty Cycle ≤ 2.0%.

ORDERING INFORMATION

Device	Package	Shipping [†]
MBRB2515L	D ² PAK	50 Units / Rail
MBRB2515LG	D ² PAK (Pb-Free)	50 Units / Rail
MBRB2515LT4	D ² PAK	800 Units / Tape & Reel
MBRB2515LT4G	D ² PAK (Pb-Free)	800 Units / Tape & Reel

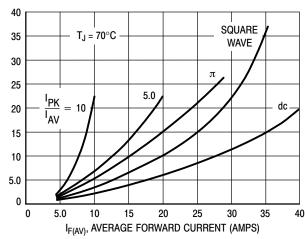
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



1000 REVERSE LEAKAGE CURRENT (mA) 400 200 $T_J = 100^{\circ}C$ 100 40 70°C 20 10 4.0 25°C 2.0 1.0 0.4 0.2 0.1 0.04 څ 0.02 0.01 0 8.0 V_R, REVERSE VOLTAGE (VOLTS)

Figure 1. Typical Forward Voltage

Figure 2. Typical Reverse Leakage Current



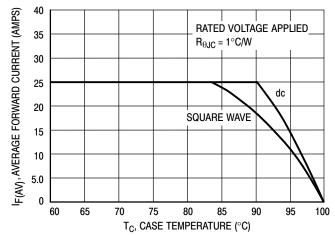


Figure 3. Typical Forward Power Dissipation

Figure 4. Current Derating, Case

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MECHANICAL CASE OUTLINE

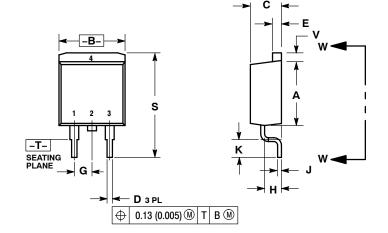




D²PAK 3 CASE 418B-04 **ISSUE L**

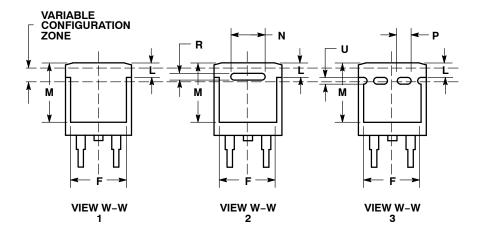
DATE 17 FEB 2015

SCALE 1:1



- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: INCH.
- 3. 418B-01 THRU 418B-03 OBSOLETE, NEW STANDARD 418B-04.

	INC	HES	MILLIM	IETERS
ым	MIN	MAX	MIN MAX	
Α	0.340	0.380	8.64	9.65
В	0.380	0.405	9.65	10.29
С	0.160	0.190	4.06	4.83
D	0.020	0.035	0.51	0.89
E	0.045	0.055	1.14	1.40
F	0.310	0.350	7.87	8.89
G	0.100 BSC		2.54 BSC	
Н	0.080	0.110	2.03	2.79
J	0.018	0.025	0.46	0.64
K	0.090	0.110	2.29	2.79
L	0.052	0.072	1.32	1.83
M	0.280	0.320	7.11	8.13
N	0.197 REF		5.00	REF
Р	0.079 REF 2.00 RE		REF	
R	0.039	0.039 REF		REF
S	0.575	0.625	14.60	15.88
V	0.045	0.055	1.14	1.40



STYLE 1: PIN 1. BASE 2. COLLECTOR
3. EMITTER
4. COLLECTOR STYLE 2: PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN STYLE 3: PIN 1. ANODE 2. CATHODE 3. ANODE 4. CATHODE

STYLE 4:

PIN 1. GATE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

STYLE 5: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. ANODE

STYLE 6: PIN 1. NO CONNECT 2. CATHODE 3. ANODE 4. CATHODE

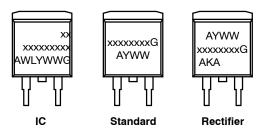
MARKING INFORMATION AND FOOTPRINT ON PAGE 2

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DATE 17 FEB 2015

GENERIC MARKING DIAGRAM*



xx = Specific Device Code A = Assembly Location

 WL
 = Wafer Lot

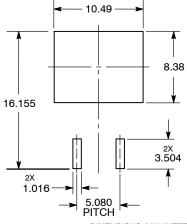
 Y
 = Year

 WW
 = Work Week

 G
 = Pb-Free Package

 AKA
 = Polarity Indicator

SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

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^{*}This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, "G" or microdot " ■", may or may not be present.

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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